

L Number	Hits	Search Text	DB	Time stamp
2	4609	(257/735-738,777-786).CCLS.	USPAT	2003/01/16 15:46
3	6729	((427/372.2,375,384,385.5,386,407.1).CCLS.	USPAT	2003/01/16 15:50
4	1753	(438/612-618).CCLS.	USPAT	2003/01/16 15:50
5	3129	((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)	USPAT	2003/01/16 15:55
6	2010	((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)	USPAT	2003/01/16 15:56
7	210	((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy) and fatigue	USPAT	2003/01/16 15:57
8	171	((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy) and fatigue) and (solidif\$4 solidification densif\$4 densification harden\$3 cur\$3)	USPAT	2003/01/16 15:59
9	103	((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy) and fatigue) and (solidif\$4 solidification densif\$4 densification harden\$3 cur\$3)) and (solvent flux\$4)	USPAT	2003/01/16 16:27
10	914	((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy) and (wafer\$1 substrate\$1) same (cut\$4 dic\$3 singulat\$3 sever\$3)	USPAT	2003/01/16 16:26
11	851	((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy) and (wafer\$1 substrate\$1) same (cut\$4 dic\$3 singulat\$3 sever\$3)) not ((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy) and fatigue) and (solidif\$4 solidification densif\$4 densification harden\$3 cur\$3)) and (solvent flux\$4))	USPAT	2003/01/16 16:26

12	344	(((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (wafer\$1 substrate\$1) same (cut\$4 dic\$3 singulat\$3 sever\$3)) not (((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (fatigue) and (solidif\$4 solidification densif\$4 densification harden\$3 cur\$3)) and (solvent flux\$4))) and (solvent flux\$4)	USPAT	2003/01/16 16:29
13	252	(((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (wafer\$1 substrate\$1) same (cut\$4 dic\$3 singulat\$3 sever\$3)) not (((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (fatigue) and (solidif\$4 solidification densif\$4 densification harden\$3 cur\$3)) and (solvent flux\$4))) and (solvent flux\$4)) and (fill\$3 under\$1fill\$3)	USPAT	2003/01/16 17:00
14	20	(((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (wafer\$1 substrate\$1) same (cut\$4 dic\$3 singulat\$3 sever\$3)) not (((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (fatigue) and (solidif\$4 solidification densif\$4 densification harden\$3 cur\$3)) and (solvent flux\$4))) and (solvent flux\$4)) and (fill\$3 under\$1fill\$3)) and wafer\$1 near\$3 level	USPAT	2003/01/16 17:07

15	232	((((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (wafer\$1 substrate\$1) same (cut\$4 dic\$3 singulat\$3 sever\$3)) not ((((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (fatigue) and (solidif\$4 solidification densif\$4 densification harden\$3 cur\$3)) and (solvent flux\$4))) and (solvent flux\$4)) and (fill\$3 under\$1fill\$3)) not ((((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (wafer\$1 substrate\$1) same (cut\$4 dic\$3 singulat\$3 sever\$3)) not ((((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (fatigue) and (solidif\$4 solidification densif\$4 densification harden\$3 cur\$3)) and (solvent flux\$4))) and (solvent flux\$4)) and (fill\$3 under\$1fill\$3)) and wafer\$1 near3 level)	USPAT	2003/01/16 17:07
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